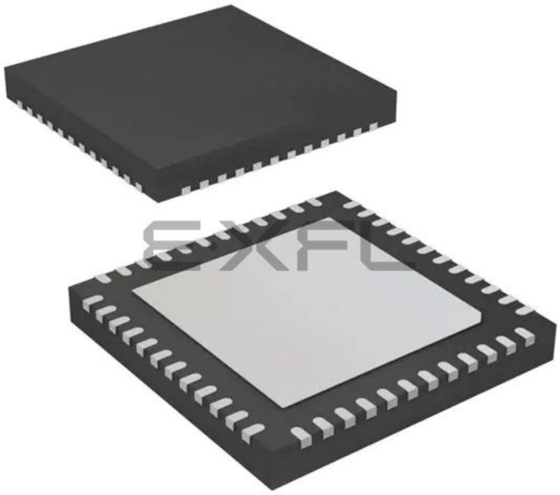
Microchip Technology - DSPIC33EP512MC204-I/MV Datasheet



What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	70 MIPs
Connectivity	I²C, IrDA, LINbus, QEI, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, Motor Control PWM, POR, PWM, WDT
Number of I/O	35
Program Memory Size	512KB (170K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	24K x 16
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 9x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	48-UFQFN Exposed Pad
Supplier Device Package	48-UQFN (6x6)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33ep512mc204-i-mv

TABLE 4-23: ECAN1 REGISTER MAP WHEN WIN (C1CTRL1<0>) = 1 FOR dsPIC33EPXXXMC/GP50X DEVICES ONLY (CONTINUED)

File Name	Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
C1RXF11EID	046E	EID<15:8>								EID<7:0>								xxxx
C1RXF12SID	0470	SID<10:3>								SID<2:0>			—	EXIDE	—	EID<17:16>		xxxx
C1RXF12EID	0472	EID<15:8>								EID<7:0>								xxxx
C1RXF13SID	0474	SID<10:3>								SID<2:0>			—	EXIDE	—	EID<17:16>		xxxx
C1RXF13EID	0476	EID<15:8>								EID<7:0>								xxxx
C1RXF14SID	0478	SID<10:3>								SID<2:0>			—	EXIDE	—	EID<17:16>		xxxx
C1RXF14EID	047A	EID<15:8>								EID<7:0>								xxxx
C1RXF15SID	047C	SID<10:3>								SID<2:0>			—	EXIDE	—	EID<17:16>		xxxx
C1RXF15EID	047E	EID<15:8>								EID<7:0>								xxxx

Legend: x = unknown value on Reset, — = unimplemented, read as ‘0’. Reset values are shown in hexadecimal.

TABLE 4-37: PMD REGISTER MAP FOR PIC24EPXXXGP20X DEVICES ONLY

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
PMD1	0760	T5MD	T4MD	T3MD	T2MD	T1MD	—	—	—	I2C1MD	U2MD	U1MD	SPI2MD	SPI1MD	—	—	AD1MD	`0000`
PMD2	0762	—	—	—	—	IC4MD	IC3MD	IC2MD	IC1MD	—	—	—	—	OC4MD	OC3MD	OC2MD	OC1MD	`0000`
PMD3	0764	—	—	—	—	—	CMPMD	—	—	CRCMD	—	—	—	—	—	I2C2MD	—	`0000`
PMD4	0766	—	—	—	—	—	—	—	—	—	—	—	—	REFOMD	CTMUMD	—	—	`0000`
PMD6	076A	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	`0000`
PMD7	076C	—	—	—	—	—	—	—	—	—	—	—	DMA0MD DMA1MD DMA2MD DMA3MD	PTGMD	—	—	—	`0000`

Legend: — = unimplemented, read as ‘`0`’. Reset values are shown in hexadecimal.

TABLE 4-38: PMD REGISTER MAP FOR PIC24EPXXXMC20X DEVICES ONLY

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
PMD1	0760	T5MD	T4MD	T3MD	T2MD	T1MD	QEI1MD	PWMMD	—	I2C1MD	U2MD	U1MD	SPI2MD	SPI1MD	—	—	AD1MD	`0000`
PMD2	0762	—	—	—	—	IC4MD	IC3MD	IC2MD	IC1MD	—	—	—	—	OC4MD	OC3MD	OC2MD	OC1MD	`0000`
PMD3	0764	—	—	—	—	—	CMPMD	—	—	CRCMD	—	—	—	—	—	I2C2MD	—	`0000`
PMD4	0766	—	—	—	—	—	—	—	—	—	—	—	—	REFOMD	CTMUMD	—	—	`0000`
PMD6	076A	—	—	—	—	—	PWM3MD	PWM2MD	PWM1MD	—	—	—	—	—	—	—	—	`0000`
PMD7	076C	—	—	—	—	—	—	—	—	—	—	—	DMA0MD DMA1MD DMA2MD DMA3MD	PTGMD	—	—	—	`0000`

Legend: — = unimplemented, read as ‘`0`’. Reset values are shown in hexadecimal.

TABLE 4-46: PORTA REGISTER MAP FOR PIC24EPXXXGP/MC206 AND dsPIC33EPXXXGP/MC206/506 DEVICES ONLY

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
TRISA	0E00	—	—	—	TRISA12	TRISA11	TRISA10	TRISA9	TRISA8	TRISA7	—	—	TRISA4	—	—	TRISA1	TRISA0	1F93
PORTA	0E02	—	—	—	RA12	RA11	RA10	RA9	RA8	RA7	—	—	RA4	—	—	RA1	RA0	0000
LATA	0E04	—	—	—	LATA12	LATA11	LATA10	LATA9	LATA8	LATA7	—	—	LATA4	—	—	LA1TA1	LA0TA0	0000
ODCA	0E06	—	—	—	ODCA12	ODCA11	ODCA10	ODCA9	ODCA8	ODCA7	—	—	ODCA4	—	—	ODCA1	ODCA0	0000
CNENA	0E08	—	—	—	CNIEA12	CNIEA11	CNIEA10	CNIEA9	CNIEA8	CNIEA7	—	—	CNIEA4	—	—	CNIEA1	CNIEA0	0000
CNPUA	0E0A	—	—	—	CNPUA12	CNPUA11	CNPUA10	CNPUA9	CNPUA8	CNPUA7	—	—	CNPUA4	—	—	CNPUA1	CNPUA0	0000
CNPDA	0E0C	—	—	—	CNPDA12	CNPDA11	CNPDA10	CNPDA9	CNPDA8	CNPDA7	—	—	CNPDA4	—	—	CNPDA1	CNPDA0	0000
ANSELA	0E0E	—	—	—	ANSA12	ANSA11	—	—	—	—	—	—	ANSA4	—	—	ANSA1	ANSA0	1813

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-47: PORTB REGISTER MAP FOR PIC24EPXXXGP/MC206 AND dsPIC33EPXXXGP/MC206/506 DEVICES ONLY

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
TRISB	0E10	TRISB15	TRISB14	TRISB13	TRISB12	TRISB11	TRISB10	TRISB9	TRISB8	TRISB7	TRISB6	TRISB5	TRISB4	TRISB3	TRISB2	TRISB1	TRISB0	FFFF
PORTB	0E12	RB15	RB14	RB13	RB12	RB11	RB10	RB9	RB8	RB7	RB6	RB5	RB4	RB3	RB2	RB1	RB0	xxxx
LATB	0E14	LATB15	LATB14	LATB13	LATB12	LATB11	LATB10	LATB9	LATB8	LATB7	LATB6	LATB5	LATB4	LATB3	LATB2	LATB1	LATB0	xxxx
ODCB	0E16	ODCB15	ODCB14	ODCB13	ODCB12	ODCB11	ODCB10	ODCB9	ODCB8	ODCB7	ODCB6	ODCB5	ODCB4	ODCB3	ODCB2	ODCB1	ODCB0	0000
CNENB	0E18	CNIEB15	CNIEB14	CNIEB13	CNIEB12	CNIEB11	CNIEB10	CNIEB9	CNIEB8	CNIEB7	CNIEB6	CNIEB5	CNIEB4	CNIEB3	CNIEB2	CNIEB1	CNIEB0	0000
CNPUB	0E1A	CNPUB15	CNPUB14	CNPUB13	CNPUB12	CNPUB11	CNPUB10	CNPUB9	CNPUB8	CNPUB7	CNPUB6	CNPUB5	CNPUB4	CNPUB3	CNPUB2	CNPUB1	CNPUB0	0000
CNPDB	0E1C	CNPDB15	CNPDB14	CNPDB13	CNPDB12	CNPDB11	CNPDB10	CNPDB9	CNPDB8	CNPDB7	CNPDB6	CNPDB5	CNPDB4	CNPDB3	CNPDB2	CNPDB1	CNPDB0	0000
ANSELB	0E1E	—	—	—	—	—	—	—	ANSB8	—	—	—	—	ANSB3	ANSB2	ANSB1	ANSB0	010F

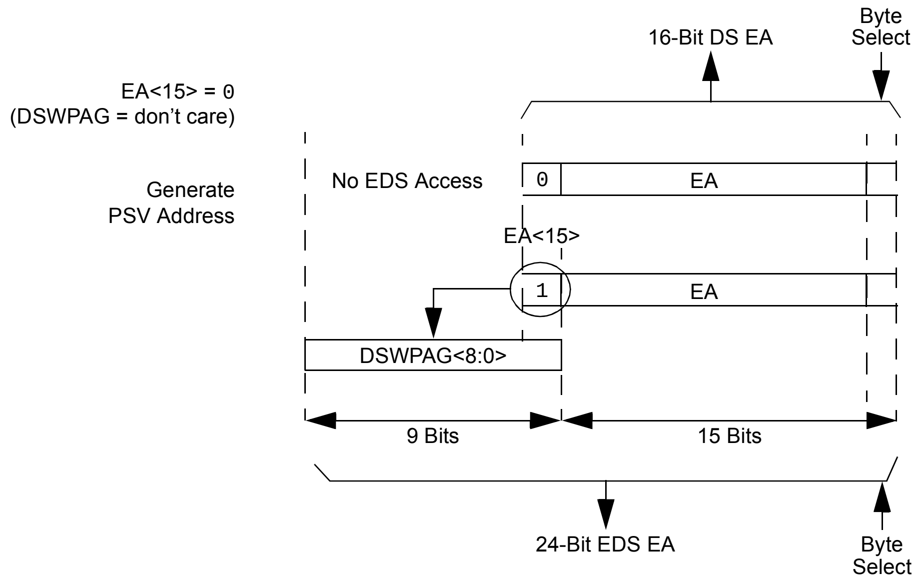
Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-48: PORTC REGISTER MAP FOR PIC24EPXXXGP/MC206 AND dsPIC33EPXXXGP/MC206/506 DEVICES ONLY

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
TRISC	0E20	TRISC15	—	TRISC13	TRISC12	TRISC11	TRISC10	TRISC9	TRISC8	TRISC7	TRISC6	TRISC5	TRISC4	TRISC3	TRISC2	TRISC1	TRISC0	BFFF
PORTC	0E22	RC15	—	RC13	RC12	RC11	RC10	RC9	RC8	RC7	RC6	RC5	RC4	RC3	RC2	RC1	RC0	xxxx
LATC	0E24	LATC15	—	LATC13	LATC12	LATC11	LATC10	LATC9	LATC8	LATC7	LATC6	LATC5	LATC4	LATC3	LATC2	LATC1	LATC0	xxxx
ODCC	0E26	ODCC15	—	ODCC13	ODCC12	ODCC11	ODCC10	ODCC9	ODCC8	ODCC7	ODCC6	ODCC5	ODCC4	ODCC3	ODCC2	ODCC1	ODCC0	0000
CNENC	0E28	CNIEC15	—	CNIEC13	CNIEC12	CNIEC11	CNIEC10	CNIEC9	CNIEC8	CNIEC7	CNIEC6	CNIEC5	CNIEC4	CNIEC3	CNIEC2	CNIEC1	CNIEC0	0000
CNPUC	0E2A	CNPUC15	—	CNPUC13	CNPUC12	CNPUC11	CNPUC10	CNPUC9	CNPUC8	CNPUC7	CNPUC6	CNPUC5	CNPUC4	CNPUC3	CNPUC2	CNPUC1	CNPUC0	0000
CNPDC	0E2C	CNPDC15	—	CNPDC13	CNPDC12	CNPDC11	CNPDC10	CNPDC9	CNPDC8	CNPDC7	CNPDC6	CNPDC5	CNPDC4	CNPDC3	CNPDC2	CNPDC1	CNPDC0	0000
ANSELC	0E2E	—	—	—	—	ANSC11	—	—	—	—	—	—	—	—	ANSC2	ANSC1	ANSC0	0807

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

EXAMPLE 4-2: EXTENDED DATA SPACE (EDS) WRITE ADDRESS GENERATION

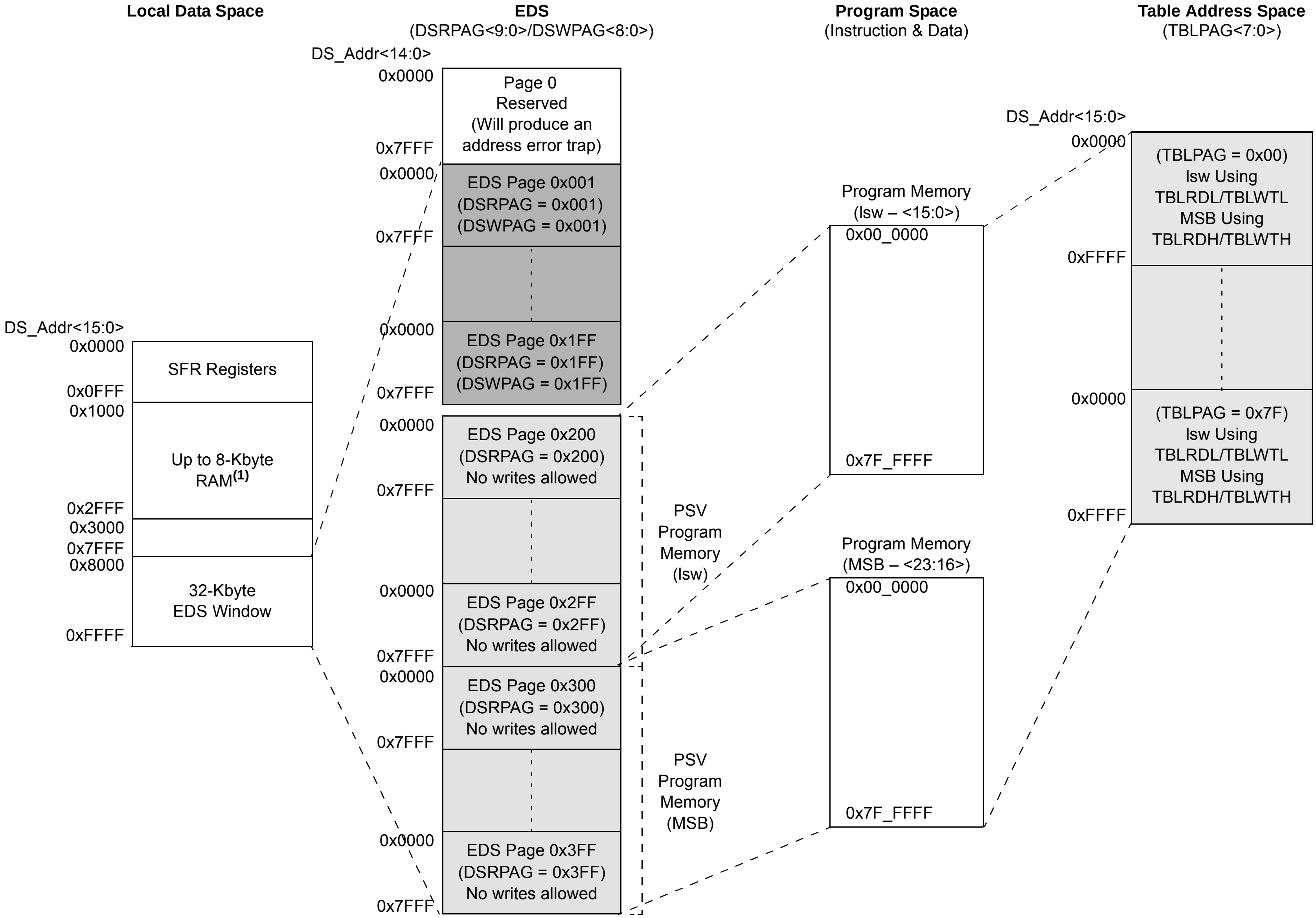


Note: DS read access when DSRPAG = 0x000 will force an address error trap.

The paged memory scheme provides access to multiple 32-Kbyte windows in the EDS and PSV memory. The Data Space Page registers, DSxPAG, in combination with the upper half of the Data Space address, can provide up to 16 Mbytes of additional address space in the EDS and 8 Mbytes (DSRPAG only) of PSV address space. The paged data memory space is shown in Example 4-3.

The Program Space (PS) can be accessed with a DSRPAG of 0x200 or greater. Only reads from PS are supported using the DSRPAG. Writes to PS are not supported, so DSWPAG is dedicated to DS, including EDS only. The Data Space and EDS can be read from, and written to, using DSRPAG and DSWPAG, respectively.

EXAMPLE 4-3: PAGED DATA MEMORY SPACE



Note 1: For 64K Flash devices. RAM size and end location is dependent on device; see **Section 4.2 "Data Address Space"** for more information.

4.5 Instruction Addressing Modes

The addressing modes shown in Table 4-63 form the basis of the addressing modes optimized to support the specific features of individual instructions. The addressing modes provided in the `MAC` class of instructions differ from those in the other instruction types.

4.5.1 FILE REGISTER INSTRUCTIONS

Most file register instructions use a 13-bit address field (f) to directly address data present in the first 8192 bytes of data memory (Near Data Space). Most file register instructions employ a working register, W0, which is denoted as WREG in these instructions. The destination is typically either the same file register or WREG (with the exception of the `MUL` instruction), which writes the result to a register or register pair. The `MOV` instruction allows additional flexibility and can access the entire Data Space.

4.5.2 MCU INSTRUCTIONS

The three-operand MCU instructions are of the form:

`Operand 3 = Operand 1 <function> Operand 2`

where Operand 1 is always a working register (that is, the addressing mode can only be Register Direct), which is referred to as Wb. Operand 2 can be a W register fetched from data memory or a 5-bit literal. The result location can either be a W register or a data memory location. The following addressing modes are supported by MCU instructions:

- Register Direct
- Register Indirect
- Register Indirect Post-Modified
- Register Indirect Pre-Modified
- 5-Bit or 10-Bit Literal

Note: Not all instructions support all the addressing modes given above. Individual instructions can support different subsets of these addressing modes.

TABLE 4-63: FUNDAMENTAL ADDRESSING MODES SUPPORTED

Addressing Mode	Description
File Register Direct	The address of the file register is specified explicitly.
Register Direct	The contents of a register are accessed directly.
Register Indirect	The contents of Wn form the Effective Address (EA).
Register Indirect Post-Modified	The contents of Wn form the EA. Wn is post-modified (incremented or decremented) by a constant value.
Register Indirect Pre-Modified	Wn is pre-modified (incremented or decremented) by a signed constant value to form the EA.
Register Indirect with Register Offset (Register Indexed)	The sum of Wn and Wb forms the EA.
Register Indirect with Literal Offset	The sum of Wn and a literal forms the EA.

TABLE 7-1: INTERRUPT VECTOR DETAILS

Interrupt Source	Vector #	IRQ #	IVT Address	Interrupt Bit Location		
				Flag	Enable	Priority
Highest Natural Order Priority						
INT0 – External Interrupt 0	8	0	0x000014	IFS0<0>	IEC0<0>	IPC0<2:0>
IC1 – Input Capture 1	9	1	0x000016	IFS0<1>	IEC0<1>	IPC0<6:4>
OC1 – Output Compare 1	10	2	0x000018	IFS0<2>	IEC0<2>	IPC0<10:8>
T1 – Timer1	11	3	0x00001A	IFS0<3>	IEC0<3>	IPC0<14:12>
DMA0 – DMA Channel 0	12	4	0x00001C	IFS0<4>	IEC0<4>	IPC1<2:0>
IC2 – Input Capture 2	13	5	0x00001E	IFS0<5>	IEC0<5>	IPC1<6:4>
OC2 – Output Compare 2	14	6	0x000020	IFS0<6>	IEC0<6>	IPC1<10:8>
T2 – Timer2	15	7	0x000022	IFS0<7>	IEC0<7>	IPC1<14:12>
T3 – Timer3	16	8	0x000024	IFS0<8>	IEC0<8>	IPC2<2:0>
SPI1E – SPI1 Error	17	9	0x000026	IFS0<9>	IEC0<9>	IPC2<6:4>
SPI1 – SPI1 Transfer Done	18	10	0x000028	IFS0<10>	IEC0<10>	IPC2<10:8>
U1RX – UART1 Receiver	19	11	0x00002A	IFS0<11>	IEC0<11>	IPC2<14:12>
U1TX – UART1 Transmitter	20	12	0x00002C	IFS0<12>	IEC0<12>	IPC3<2:0>
AD1 – ADC1 Convert Done	21	13	0x00002E	IFS0<13>	IEC0<13>	IPC3<6:4>
DMA1 – DMA Channel 1	22	14	0x000030	IFS0<14>	IEC0<14>	IPC3<10:8>
Reserved	23	15	0x000032	—	—	—
SI2C1 – I2C1 Slave Event	24	16	0x000034	IFS1<0>	IEC1<0>	IPC4<2:0>
MI2C1 – I2C1 Master Event	25	17	0x000036	IFS1<1>	IEC1<1>	IPC4<6:4>
CM – Comparator Combined Event	26	18	0x000038	IFS1<2>	IEC1<2>	IPC4<10:8>
CN – Input Change Interrupt	27	19	0x00003A	IFS1<3>	IEC1<3>	IPC4<14:12>
INT1 – External Interrupt 1	28	20	0x00003C	IFS1<4>	IEC1<4>	IPC5<2:0>
Reserved	29-31	21-23	0x00003E-0x000042	—	—	—
DMA2 – DMA Channel 2	32	24	0x000044	IFS1<8>	IEC1<8>	IPC6<2:0>
OC3 – Output Compare 3	33	25	0x000046	IFS1<9>	IEC1<9>	IPC6<6:4>
OC4 – Output Compare 4	34	26	0x000048	IFS1<10>	IEC1<10>	IPC6<10:8>
T4 – Timer4	35	27	0x00004A	IFS1<11>	IEC1<11>	IPC6<14:12>
T5 – Timer5	36	28	0x00004C	IFS1<12>	IEC1<12>	IPC7<2:0>
INT2 – External Interrupt 2	37	29	0x00004E	IFS1<13>	IEC1<13>	IPC7<6:4>
U2RX – UART2 Receiver	38	30	0x000050	IFS1<14>	IEC1<14>	IPC7<10:8>
U2TX – UART2 Transmitter	39	31	0x000052	IFS1<15>	IEC1<15>	IPC7<14:12>
SPI2E – SPI2 Error	40	32	0x000054	IFS2<0>	IEC2<0>	IPC8<2:0>
SPI2 – SPI2 Transfer Done	41	33	0x000056	IFS2<1>	IEC2<1>	IPC8<6:4>
C1RX – CAN1 RX Data Ready(1)	42	34	0x000058	IFS2<2>	IEC2<2>	IPC8<10:8>
C1 – CAN1 Event(1)	43	35	0x00005A	IFS2<3>	IEC2<3>	IPC8<14:12>
DMA3 – DMA Channel 3	44	36	0x00005C	IFS2<4>	IEC2<4>	IPC9<2:0>
IC3 – Input Capture 3	45	37	0x00005E	IFS2<5>	IEC2<5>	IPC9<6:4>
IC4 – Input Capture 4	46	38	0x000060	IFS2<6>	IEC2<6>	IPC9<10:8>
Reserved	47-56	39-48	0x000062-0x000074	—	—	—
SI2C2 – I2C2 Slave Event	57	49	0x000076	IFS3<1>	IEC3<1>	IPC12<6:4>
MI2C2 – I2C2 Master Event	58	50	0x000078	IFS3<2>	IEC3<2>	IPC12<10:8>
Reserved	59-64	51-56	0x00007A-0x000084	—	—	—
PSEM – PWM Special Event Match(2)	65	57	0x000086	IFS3<9>	IEC3<9>	IPC14<6:4>

Note 1: This interrupt source is available on dsPIC33EPXXXGP50X and dsPIC33EPXXXMC50X devices only.
2: This interrupt source is available on dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices only.

REGISTER 7-3: INTCON1: INTERRUPT CONTROL REGISTER 1

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
NSTDIS	OVAERR[(1)]	OVBERR[(1)]	COVAERR[(1)]	COVBERR[(1)]	OVATE[(1)]	OVBTE[(1)]	COVTE[(1)]
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0
SFTACERR[(1)]	DIV0ERR	DMACERR	MATHERR	ADDRERR	STKERR	OSCFAIL	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **NSTDIS:** Interrupt Nesting Disable bit
1 = Interrupt nesting is disabled
0 = Interrupt nesting is enabled

bit 14 **OVAERR:** Accumulator A Overflow Trap Flag bit[(1)]
1 = Trap was caused by overflow of Accumulator A
0 = Trap was not caused by overflow of Accumulator A

bit 13 **OVBERR:** Accumulator B Overflow Trap Flag bit[(1)]
1 = Trap was caused by overflow of Accumulator B
0 = Trap was not caused by overflow of Accumulator B

bit 12 **COVAERR:** Accumulator A Catastrophic Overflow Trap Flag bit[(1)]
1 = Trap was caused by catastrophic overflow of Accumulator A
0 = Trap was not caused by catastrophic overflow of Accumulator A

bit 11 **COVBERR:** Accumulator B Catastrophic Overflow Trap Flag bit[(1)]
1 = Trap was caused by catastrophic overflow of Accumulator B
0 = Trap was not caused by catastrophic overflow of Accumulator B

bit 10 **OVATE:** Accumulator A Overflow Trap Enable bit[(1)]
1 = Trap overflow of Accumulator A
0 = Trap is disabled

bit 9 **OVBTE:** Accumulator B Overflow Trap Enable bit[(1)]
1 = Trap overflow of Accumulator B
0 = Trap is disabled

bit 8 **COVTE:** Catastrophic Overflow Trap Enable bit[(1)]
1 = Trap on catastrophic overflow of Accumulator A or B is enabled
0 = Trap is disabled

bit 7 **SFTACERR:** Shift Accumulator Error Status bit[(1)]
1 = Math error trap was caused by an invalid accumulator shift
0 = Math error trap was not caused by an invalid accumulator shift

bit 6 **DIV0ERR:** Divide-by-Zero Error Status bit
1 = Math error trap was caused by a divide-by-zero
0 = Math error trap was not caused by a divide-by-zero

bit 5 **DMACERR:** DMAC Trap Flag bit
1 = DMAC trap has occurred
0 = DMAC trap has not occurred

Note 1: These bits are available on dsPIC33EPXXXMC20X/50X and dsPIC33EPXXXGP50X devices only.

BUFFER 21-5: ECAN™ MESSAGE BUFFER WORD 4

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
Byte 3							
bit 15							bit 8

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
Byte 2							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-8	**Byte 3<15:8>:** ECAN Message Byte 3 bits
bit 7-0	**Byte 2<7:0>:** ECAN Message Byte 2 bits

BUFFER 21-6: ECAN™ MESSAGE BUFFER WORD 5

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
Byte 5							
bit 15							bit 8

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
Byte 4							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-8	**Byte 5<15:8>:** ECAN Message Byte 5 bits
bit 7-0	**Byte 4<7:0>:** ECAN Message Byte 4 bits

22.0 CHARGE TIME MEASUREMENT UNIT (CTMU)

Note 1: This data sheet summarizes the features of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"Charge Time Measurement Unit (CTMU)"** (DS70661) in the "*dsPIC33/PIC24 Family Reference Manual*", which is available on the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

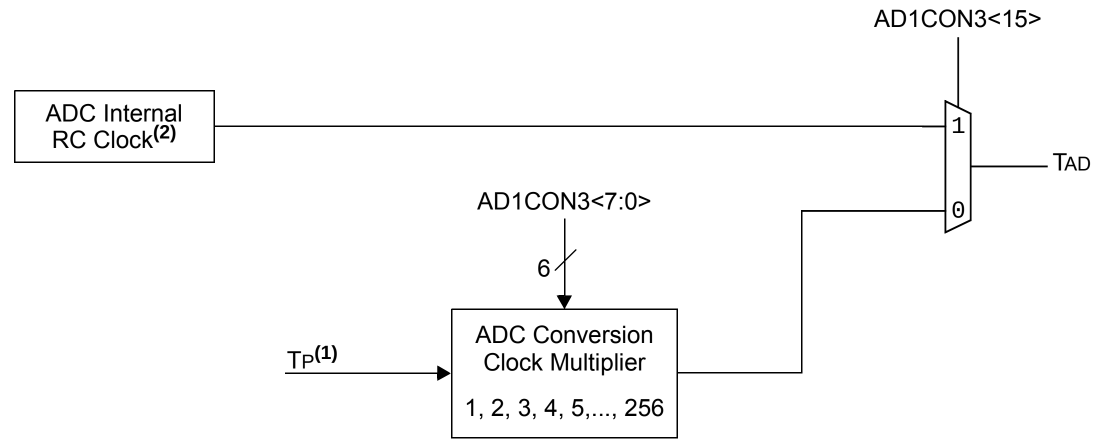
The Charge Time Measurement Unit is a flexible analog module that provides accurate differential time measurement between pulse sources, as well as asynchronous pulse generation. Its key features include:

- Four Edge Input Trigger Sources
- Polarity Control for Each Edge Source
- Control of Edge Sequence
- Control of Response to Edges
- Precise Time Measurement Resolution of 1 ns
- Accurate Current Source Suitable for Capacitive Measurement
- On-Chip Temperature Measurement using a Built-in Diode

Together with other on-chip analog modules, the CTMU can be used to precisely measure time, measure capacitance, measure relative changes in capacitance or generate output pulses that are independent of the system clock.

The CTMU module is ideal for interfacing with capacitive-based sensors.The CTMU is controlled through three registers: CTMUCON1, CTMUCON2 and CTMUICON. CTMUCON1 and CTMUCON2 enable the module and control edge source selection, edge source polarity selection and edge sequencing. The CTMUICON register controls the selection and trim of the current source.

FIGURE 23-2: ADC CONVERSION CLOCK PERIOD BLOCK DIAGRAM



Note 1: TP = 1/FP.

2: See the ADC electrical specifications in **Section 30.0 “Electrical Characteristics”** for the exact RC clock value.

REGISTER 24-12: PTGQPTR: PTG STEP QUEUE POINTER REGISTER(1)

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	—	PTGQPTR<4:0>				
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-5	**Unimplemented:** Read as ‘0’
bit 4-0	**PTGQPTR<4:0>:** PTG Step Queue Pointer Register bits This register points to the currently active Step command in the Step queue.

Note 1: This register is read-only when the PTG module is executing Step commands (PTGEN = 1 and PTGSTRT = 1).

REGISTER 24-13: PTGQUEx: PTG STEP QUEUE REGISTER x (x = 0-7)(1,3)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
STEP(2x + 1)<7:0>(2)							
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
STEP(2x)<7:0>(2)							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-8	**STEP(2x + 1)<7:0>:** PTG Step Queue Pointer Register bits(2) A queue location for storage of the STEP(2x + 1) command byte.
bit 7-0	**STEP(2x)<7:0>:** PTG Step Queue Pointer Register bits(2) A queue location for storage of the STEP(2x) command byte.

Note 1: This register is read-only when the PTG module is executing Step commands (PTGEN = 1 and PTGSTRT = 1).

2: Refer to Table 24-1 for the Step command encoding.

3: The Step registers maintain their values on any type of Reset.

FIGURE 25-2: COMPARATOR MODULE BLOCK DIAGRAM (MODULE 4)

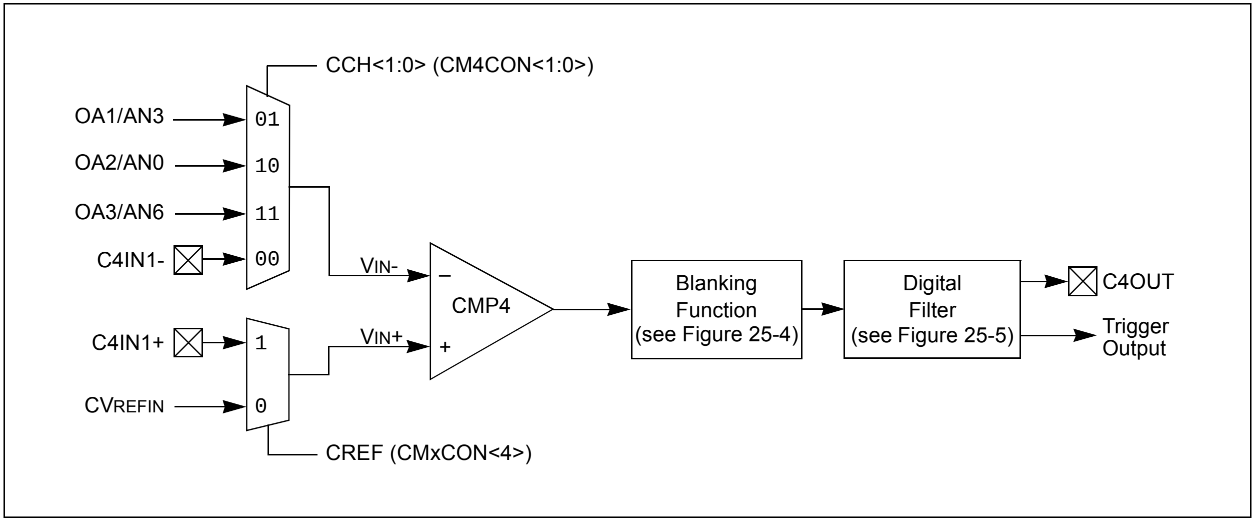
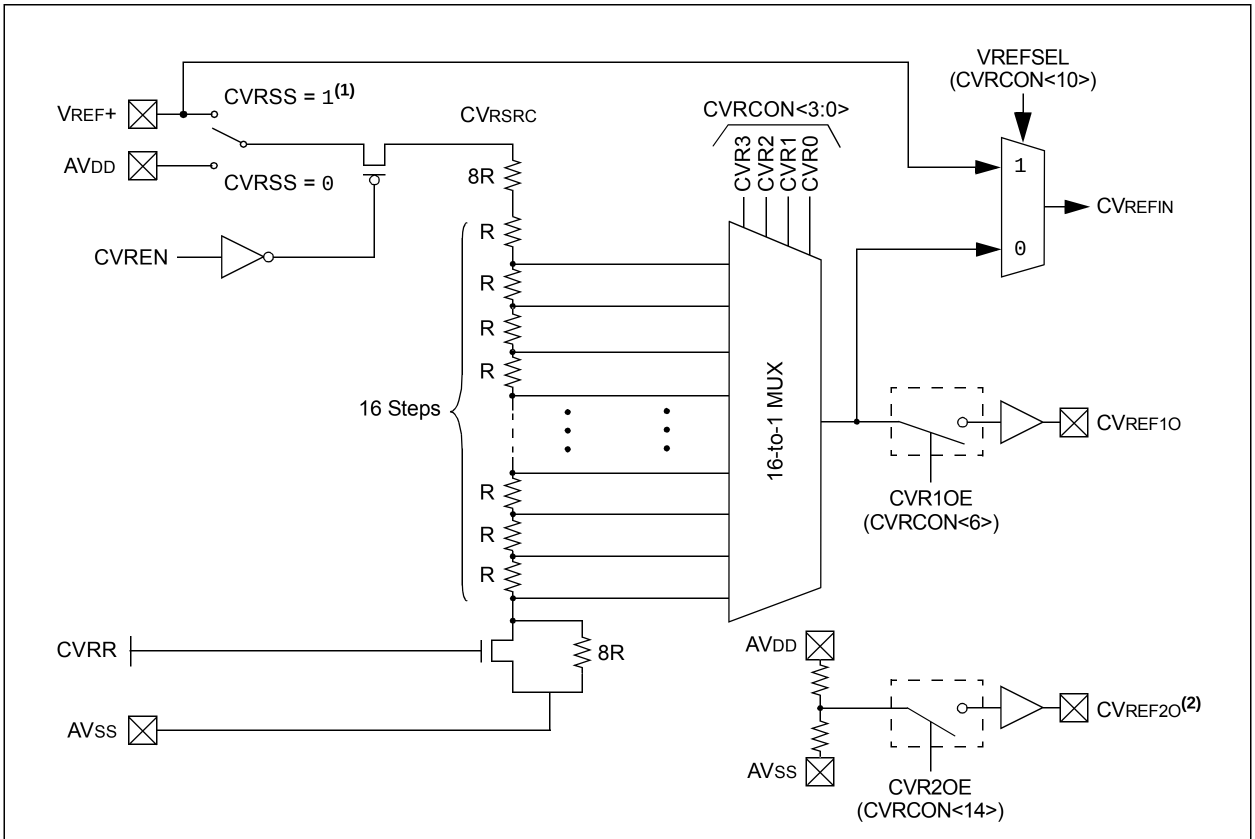


FIGURE 25-3: OP AMP/COMPARATOR VOLTAGE REFERENCE BLOCK DIAGRAM



Note 1: In order to operate with CVRSS = `1`, at least one of the comparator modules must be enabled.

2: This reference is (AVDD + AVSS)/2.

TABLE 30-9: DC CHARACTERISTICS: WATCHDOG TIMER DELTA CURRENT (ΔI_{WDT})(1)

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ T_A ≤ +85°C for Industrial -40°C ≤ T_A ≤ +125°C for Extended		
Parameter No.	**Typ.**	**Max.**	**Units**	**Conditions**	
DC61d	8	—	μA	-40°C	3.3V
DC61a	10	—	μA	+25°C	
DC61b	12	—	μA	+85°C	
DC61c	13	—	μA	+125°C	

Note 1: The ΔI_{WDT} current is the additional current consumed when the module is enabled. This current should be added to the base I_{PD} current. All parameters are characterized but not tested during manufacturing.

TABLE 30-10: DC CHARACTERISTICS: DOZE CURRENT (I_{DOZE})

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ T_A ≤ +85°C for Industrial -40°C ≤ T_A ≤ +125°C for Extended				
Parameter No.	**Typ.**	**Max.**	**Doze Ratio**	**Units**	**Conditions**		
Doze Current (I_{DOZE})(1)							
DC73a(2)	35	—	1:2	mA	-40°C	3.3V	F_{OSC} = 140 MHz
DC73g	20	30	1:128	mA			
DC70a(2)	35	—	1:2	mA	+25°C	3.3V	F_{OSC} = 140 MHz
DC70g	20	30	1:128	mA			
DC71a(2)	35	—	1:2	mA	+85°C	3.3V	F_{OSC} = 140 MHz
DC71g	20	30	1:128	mA			
DC72a(2)	28	—	1:2	mA	+125°C	3.3V	F_{OSC} = 120 MHz
DC72g	15	30	1:128	mA			

Note 1: I_{DOZE} is primarily a function of the operating voltage and frequency. Other factors, such as I/O pin loading and switching rate, oscillator type, internal code execution pattern and temperature, also have an impact on the current consumption. The test conditions for all I_{DOZE} measurements are as follows:

- Oscillator is configured in EC mode and external clock is active, OSC1 is driven with external square wave from rail-to-rail (EC clock overshoot/undershoot < 250 mV required)
- CLKO is configured as an I/O input pin in the Configuration Word
- All I/O pins are configured as inputs and pulled to V_{SS}
- $\overline{MCLR}$ = V_{DD}, WDT and FSCM are disabled
- CPU, SRAM, program memory and data memory are operational
- No peripheral modules are operating; however, every peripheral is being clocked (all PMDx bits are zeroed)
- CPU is executing `while(1)` statement
- JTAG is disabled

2: Parameter is characterized but not tested in manufacturing.

TABLE 30-11: DC CHARACTERISTICS: I/O PIN INPUT SPECIFICATIONS

DC CHARACTERISTICS			**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
	V_{IL}	**Input Low Voltage**					
DI10		Any I/O Pin and $\overline{MCLR}$	V_{SS}	—	0.2 V_{DD}	V	
DI18		I/O Pins with SDAx, SCLx	V_{SS}	—	0.3 V_{DD}	V	SMBus disabled
DI19		I/O Pins with SDAx, SCLx	V_{SS}	—	0.8	V	SMBus enabled
	V_{IH}	**Input High Voltage**					
DI20		I/O Pins Not 5V Tolerant	0.8 V_{DD}	—	V_{DD}	V	**(Note 3)**
		I/O Pins 5V Tolerant and $\overline{MCLR}$	0.8 V_{DD}	—	5.5	V	**(Note 3)**
		I/O Pins with SDAx, SCLx	0.8 V_{DD}	—	5.5	V	SMBus disabled
		I/O Pins with SDAx, SCLx	2.1	—	5.5	V	SMBus enabled
	I_{CNPU}	**Change Notification Pull-up Current**					
DI30			150	250	550	μA	V_{DD} = 3.3V, V_{PIN} = V_{SS}
	I_{CNPD}	**Change Notification Pull-Down Current**$^{(4)}$					
DI31			20	50	100	μA	V_{DD} = 3.3V, V_{PIN} = V_{DD}

Note 1: The leakage current on the $\overline{MCLR}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current can be measured at different input voltages.

2: Negative current is defined as current sourced by the pin.

3: See the **"Pin Diagrams"** section for the 5V tolerant I/O pins.

4: V_{IL} source < (V_{SS} – 0.3). Characterized but not tested.

5: Non-5V tolerant pins V_{IH} source > (V_{DD} + 0.3), 5V tolerant pins V_{IH} source > 5.5V. Characterized but not tested.

6: Digital 5V tolerant pins cannot tolerate any "positive" input injection current from input sources > 5.5V.

7: Non-zero injection currents can affect the ADC results by approximately 4-6 counts.

8: Any number and/or combination of I/O pins not excluded under I_{ICL} or I_{ICH} conditions are permitted provided the mathematical "absolute instantaneous" sum of the input injection currents from all pins do not exceed the specified limit. Characterized but not tested.

FIGURE 30-9: HIGH-SPEED PWMx MODULE FAULT TIMING CHARACTERISTICS (dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X DEVICES ONLY)

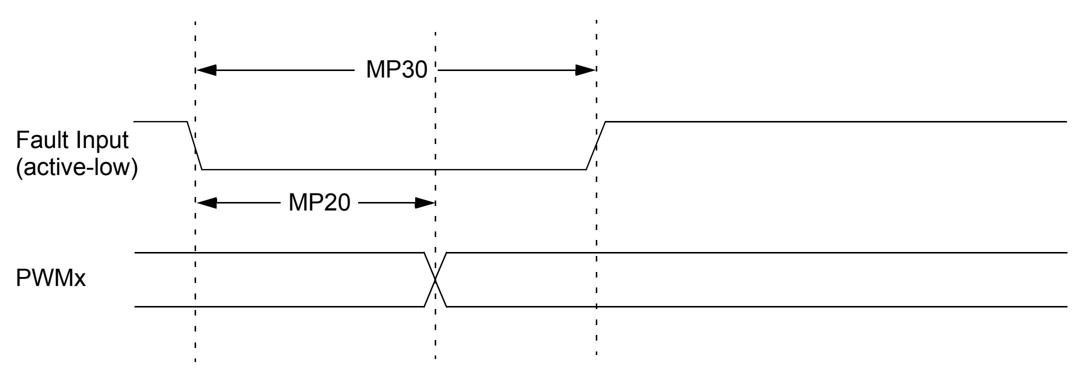
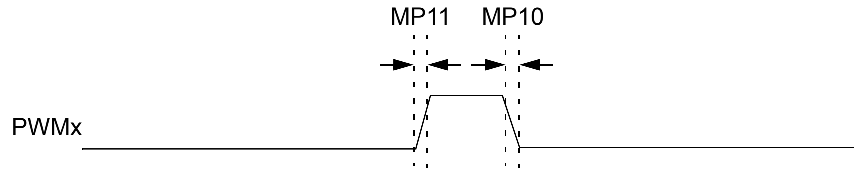


FIGURE 30-10: HIGH-SPEED PWMx MODULE TIMING CHARACTERISTICS (dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X DEVICES ONLY)



Note: Refer to Figure 30-1 for load conditions.

TABLE 30-29: HIGH-SPEED PWMx MODULE TIMING REQUIREMENTS (dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X DEVICES ONLY)

AC CHARACTERISTICS			**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic[1]**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
MP10	TFPWM	PWMx Output Fall Time	—	—	—	ns	See Parameter DO32
MP11	TRPWM	PWMx Output Rise Time	—	—	—	ns	See Parameter DO31
MP20	TFD	Fault Input ↓ to PWMx I/O Change	—	—	15	ns	
MP30	TFH	Fault Input Pulse Width	15	—	—	ns	

Note 1: These parameters are characterized but not tested in manufacturing.

TABLE 30-47: SPI1 SLAVE MODE (FULL-DUPLEX, CKE = `0`, CKP = `1`, SMP = `0`) TIMING REQUIREMENTS

AC CHARACTERISTICS			**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ T_A ≤ +85°C for Industrial -40°C ≤ T_A ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic[1]**	**Min.**	**Typ.[2]**	**Max.**	**Units**	**Conditions**
SP70	FscP	Maximum SCK1 Input Frequency	—	—	15	MHz	**(Note 3)**
SP72	TscF	SCK1 Input Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP73	TscR	SCK1 Input Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP30	TdoF	SDO1 Data Output Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP31	TdoR	SDO1 Data Output Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP35	TscH2doV, TscL2doV	SDO1 Data Output Valid after SCK1 Edge	—	6	20	ns	
SP36	TdoV2scH, TdoV2scL	SDO1 Data Output Setup to First SCK1 Edge	30	—	—	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDI1 Data Input to SCK1 Edge	30	—	—	ns	
SP41	TscH2diL, TscL2diL	Hold Time of SDI1 Data Input to SCK1 Edge	30	—	—	ns	
SP50	TssL2scH, TssL2scL	$\overline{\text{SS1}}$ ↓ to SCK1 ↑ or SCK1 ↓ Input	120	—	—	ns	
SP51	TssH2doZ	$\overline{\text{SS1}}$ ↑ to SDO1 Output High-Impedance	10	—	50	ns	**(Note 4)**
SP52	TscH2ssH, TscL2ssH	$\overline{\text{SS1}}$ ↑ after SCK1 Edge	1.5 TCY + 40	—	—	ns	**(Note 4)**

Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in “Typical” column is at 3.3V, +25°C unless otherwise stated.

3: The minimum clock period for SCK1 is 66.7 ns. Therefore, the SCK1 clock generated by the master must not violate this specification.

4: Assumes 50 pF load on all SPI1 pins.

FIGURE 30-34: ECANx MODULE I/O TIMING CHARACTERISTICS

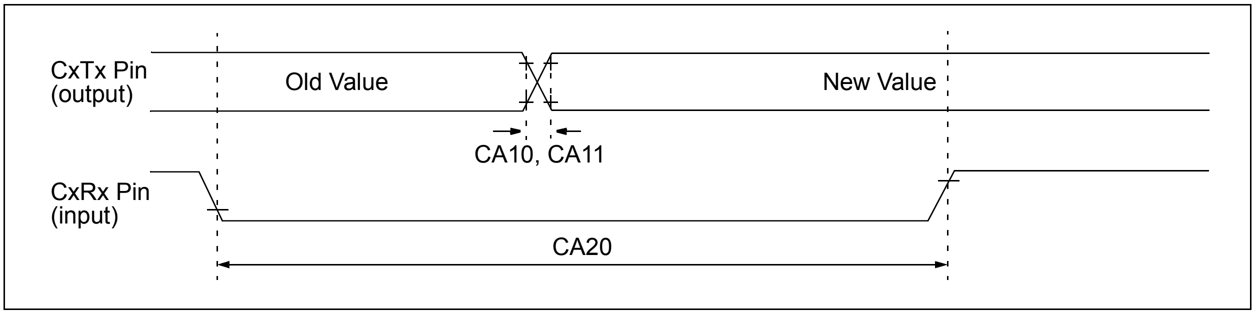


TABLE 30-51: ECANx MODULE I/O TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic[1]**	**Min.**	**Typ.[2]**	**Max.**	**Units**	**Conditions**
CA10	TIOF	Port Output Fall Time	—	—	—	ns	See Parameter DO32
CA11	TIOR	Port Output Rise Time	—	—	—	ns	See Parameter DO31
CA20	TCWF	Pulse Width to Trigger CAN Wake-up Filter	120	—	—	ns	

Note 1: These parameters are characterized but not tested in manufacturing.

2: Data in “Typical” column is at 3.3V, +25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

FIGURE 30-35: UARTx MODULE I/O TIMING CHARACTERISTICS

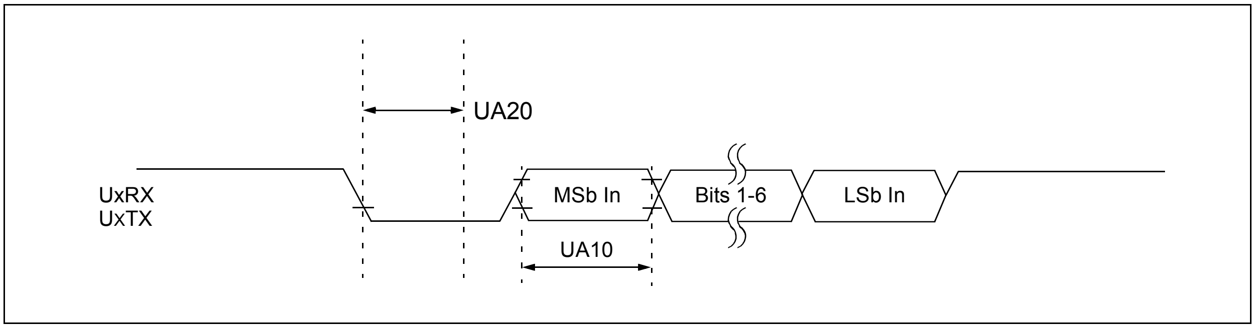


TABLE 30-52: UARTx MODULE I/O TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +125°C				
Param No.	**Symbol**	**Characteristic[1]**	**Min.**	**Typ.[2]**	**Max.**	**Units**	**Conditions**
UA10	TUABAUD	UARTx Baud Time	66.67	—	—	ns	
UA11	FBAUD	UARTx Baud Frequency	—	—	15	Mbps	
UA20	TCWF	Start Bit Pulse Width to Trigger UARTx Wake-up	500	—	—	ns	

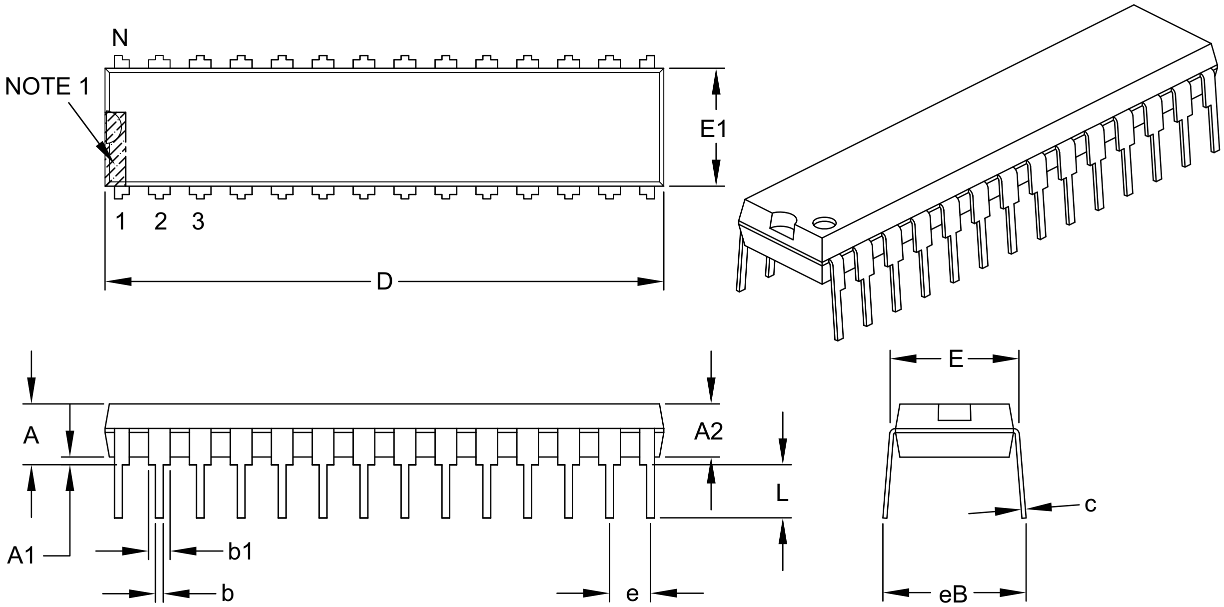
Note 1: These parameters are characterized but not tested in manufacturing.

2: Data in “Typical” column is at 3.3V, +25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

33.2 Package Details

28-Lead Skinny Plastic Dual In-Line (SP) – 300 mil Body [SPDIP]

Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		INCHES		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N	28		
Pitch	e	.100 BSC		
Top to Seating Plane	A	–	–	.200
Molded Package Thickness	A2	.120	.135	.150
Base to Seating Plane	A1	.015	–	–
Shoulder to Shoulder Width	E	.290	.310	.335
Molded Package Width	E1	.240	.285	.295
Overall Length	D	1.345	1.365	1.400
Tip to Seating Plane	L	.110	.130	.150
Lead Thickness	c	.008	.010	.015
Upper Lead Width	b1	.040	.050	.070
Lower Lead Width	b	.014	.018	.022
Overall Row Spacing §	eB	–	–	.430

Notes:

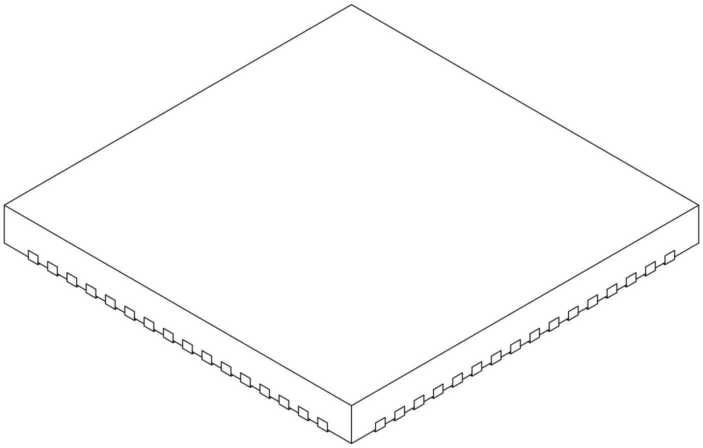
1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic.
3. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-070B

64-Lead Plastic Quad Flat, No Lead Package (MR) – 9x9x0.9 mm Body with 5.40 x 5.40 Exposed Pad [QFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N	64		
Pitch	e	0.50 BSC		
Overall Height	A	0.80	0.90	1.00
Standoff	A1	0.00	0.02	0.05
Contact Thickness	A3	0.20 REF		
Overall Width	E	9.00 BSC		
Exposed Pad Width	E2	5.30	5.40	5.50
Overall Length	D	9.00 BSC		
Exposed Pad Length	D2	5.30	5.40	5.50
Contact Width	b	0.20	0.25	0.30
Contact Length	L	0.30	0.40	0.50
Contact-to-Exposed Pad	K	0.20	-	-

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated.
3. Dimensioning and tolerancing per ASME Y14.5M.

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-154A Sheet 2 of 2